

## **Description**

The VSM0103 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

•  $V_{DS} = 100V, I_{D} = 3A$ 

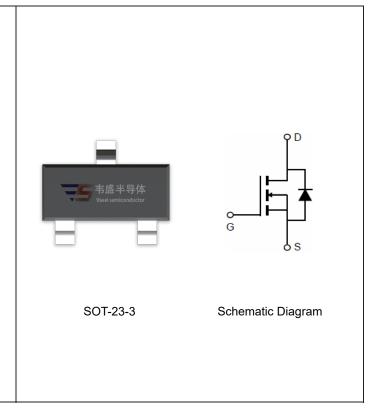
 $R_{DS(ON)}\,{<}160m\Omega\; @\; V_{GS}{=}10V \quad (Typ:136m\Omega)$ 

 $R_{DS(ON)}$  <170m $\Omega$  @  $V_{GS}$ =4.5V (Typ:140m $\Omega$ )

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

### **Application**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



## **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM0103-S2	VSM0103	SOT-23-3	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	100	V	
Gate-Source Voltage	V <sub>G</sub> S	±20	V	
Drain Current-Continuous	I <sub>D</sub>	3	Α	
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	20	Α	
Maximum Power Dissipation	P <sub>D</sub>	1.5	W	
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 175	$^{\circ}\mathbb{C}$	

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	R <sub>0JA</sub>	100	°C/W
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# **Electrical Characteristics (T<sub>A</sub>=25**°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	100	-	-	V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V	-	-	1	μA	



Parameter	Symbol	Condition	Min	Тур	Max	Unit		
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20 $V$ , $V_{DS}$ =0 $V$	-	-	±100	nA		
On Characteristics (Note 3)								
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.0	1.5	2.0	V		
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3A	-	136	160	mΩ		
Diam-Source On-State Resistance		V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	-	140	170			
Forward Transconductance	<b>G</b> FS	$V_{DS}=5V,I_{D}=3A$	-	5	-	S		
Dynamic Characteristics (Note4)			•	•		•		
Input Capacitance	C <sub>lss</sub>	\/ -50\/\/ -0\/	-	650	-	PF		
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1.0MHz	-	24	-	PF		
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.UIVITZ	-	20	-	PF		
Switching Characteristics (Note 4)								
Turn-on Delay Time	t <sub>d(on)</sub>		-	6	-	nS		
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =50V, $R_L$ =19 $\Omega$	-	4	-	nS		
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{G}$ =3 $\Omega$	-	20	-	nS		
Turn-Off Fall Time	t <sub>f</sub>		-	4	-	nS		
Total Gate Charge	Qg	\/ F0\/ L 0A	-	20		nC		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}=50V, I_{D}=3A,$	-	2.1	-	nC		
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V	-	3.3	-	nC		
Drain-Source Diode Characteristics			•			•		
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	$V_{GS}=0V,I_{S}=3A$	-	-	1.2	V		
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	3	Α		

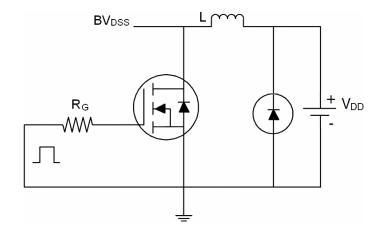
### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to productio

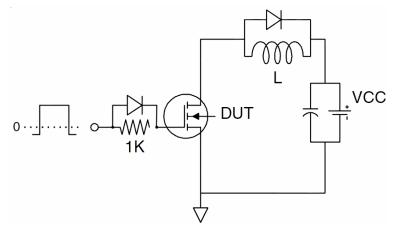


# **Test Circuit**

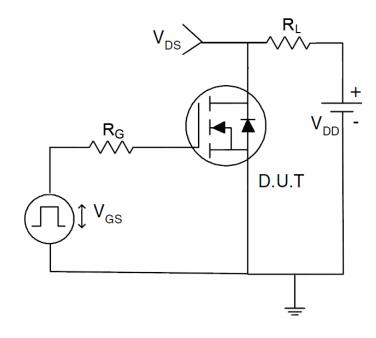
# 1) E<sub>AS</sub> test circuit



# 2) Gate charge test circuit

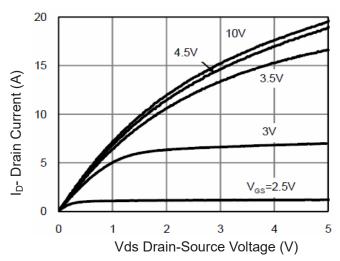


# 3) Switch Time Test Circuit

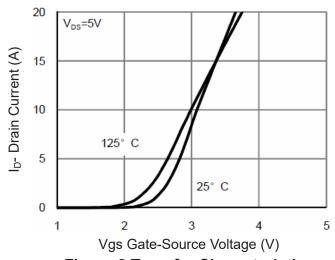




# **Typical Electrical and Thermal Characteristics (Curves)**



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

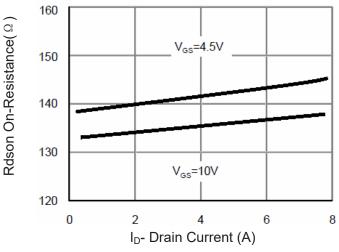


Figure 3 Rdson-Drain Current

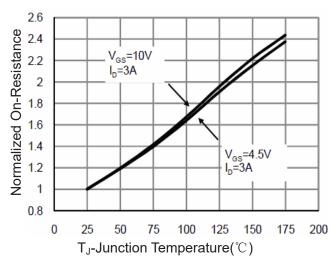


Figure 4 Rdson-JunctionTemperature

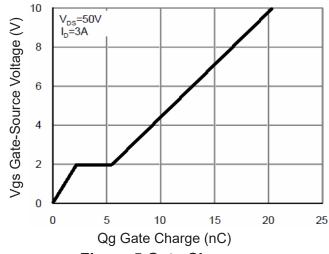


Figure 5 Gate Charge

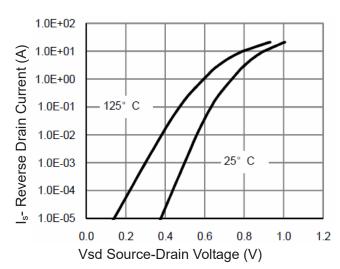
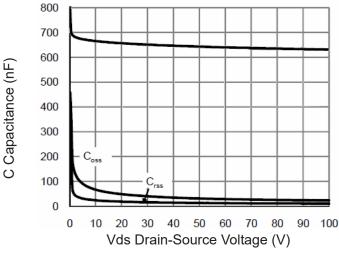


Figure 6 Source- Drain Diode Forward

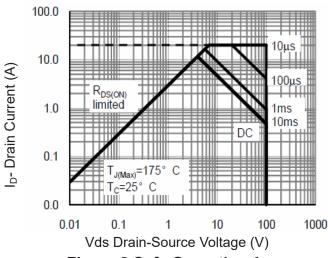




3 2.5 Ip- Drain Current (A) 2 1.5 1.0 0.5 0 0 25 50 75 100 125 150 175 T<sub>J</sub>-Junction Temperature(°C)

Figure 7 Capacitance vs Vds

Figure 9 BV<sub>DSS</sub> vs Junction Temperature



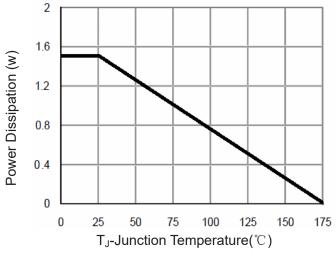
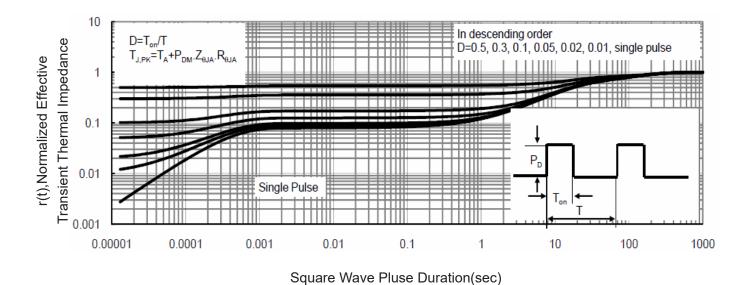


Figure 8 Safe Operation Area

Figure 10 Power De-rating



**Figure 11 Normalized Maximum Transient Thermal Impedance**